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AMENDMENT UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP 1775  
PATENT APPLICATION

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q67726

**RECEIVED**

Mitsuo OSADA, et al.

**MAR 09 2004**

Appln. No.: 10/009,822

Group Art Unit: 1775

Confirmation No.: 6202

Examiner: LAVILLA, MICHAEL E

Filed: December 13, 2001

For: MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC PACKAGE USING THE SAME

**AMENDMENT UNDER 37 C.F.R. § 1.116**

**MAIL STOP AF**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated December 5, 2003, please amend the above-identified application as follows on the accompanying pages.

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me  
4/2/04